



## Material Content Data Sheet



<b>Sales Product Name</b>		IPT012N08N5		<b>Issued</b>		24. January 2018			
<b>MA#</b>		MA001238926							
<b>Package</b>		PG-HSOF-8-1		<b>Weight*</b>		772.86 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.025	0.91	0.91	9090	9090	
leadframe	non noble metal	iron	7439-89-6	0.421	0.05		544		
	inorganic material	phosphorus	7723-14-0	0.126	0.02		163		
	non noble metal	copper	7440-50-8	420.040	54.34	54.41	543486	544193	
wire	non noble metal	aluminium	7429-90-5	14.422	1.87	1.87	18660	18660	
encapsulation	organic material	carbon black	1333-86-4	4.767	0.62		6168		
	plastics	epoxy resin	-	52.438	6.78		67849		
	inorganic material	silicondioxide	60676-86-0	260.603	33.72	41.12	337191	411208	
leadfinish	non noble metal	tin	7440-31-5	6.479	0.84	0.84	8383	8383	
plating	non noble metal	nickel	7440-02-0	0.526	0.07		680		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.07	2	682	
solder	noble metal	silver	7440-22-4	0.150	0.02		195		
	non noble metal	tin	7440-31-5	0.120	0.02		156		
	non noble metal	lead	7439-92-1	5.745	0.74	0.78	7433	7784	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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